

# MC10H123

## Triple 4-3-3-Input Bus Driver

### Description

The MC10H123 is a triple 4-3-3-Input Bus Driver.

The MC10H123 consists of three NOR gates designed for bus driving applications on card or between cards. Output low logic levels are specified with  $V_{OL} = -2.1$  Vdc so that the bus may be terminated to  $-2.0$  Vdc. The gate output, when low, appears as a high impedance to the bus, because the output emitter-followers of the MC10H123 are “turned-off.” This eliminates discontinuities in the characteristic impedance of the bus.

The  $V_{OH}$  level is specified when driving a  $25\ \Omega$  load terminated to  $-2.0$  Vdc, the equivalent of a  $50\ \Omega$  bus terminated at both ends. Although  $25\ \Omega$  is the lowest characteristic impedance that can be driven by the MC10H123, higher impedance values may be used with this part. A typical  $50\ \Omega$  bus is shown in Figure 3.

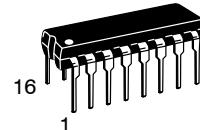
### Features

- Propagation Delay, 1.5 ns Typical
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K™ Compatible
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

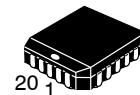


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PDIP-16  
P SUFFIX  
CASE 648-08

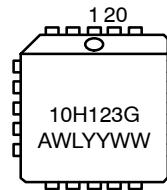


PLCC-20  
FN SUFFIX  
CASE 775-02

### MARKING DIAGRAMS\*



PDIP-16



PLCC-20

A = Assembly Location  
WL, L = Wafer Lot  
YY, Y = Year  
WW, W = Work Week  
G = Pb-Free Package

\*For additional marking information, refer to Application Note [AND8002/D](#).

### ORDERING INFORMATION

Device	Package	Shipping†
MC10H123FNG	PLCC-20 (Pb-Free)	46 Units / Tube
MC10H123FNR2G	PLCC-20 (Pb-Free)	500 Tape & Reel
MC10H123PG	PDIP-16 (Pb-Free)	25 Units / Tube

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

# MC10H123

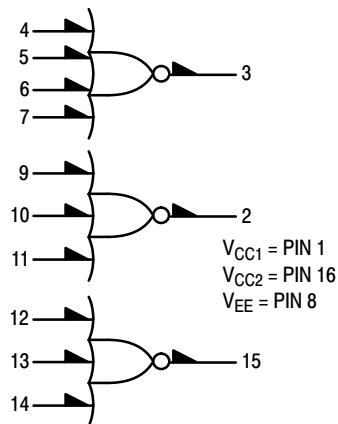
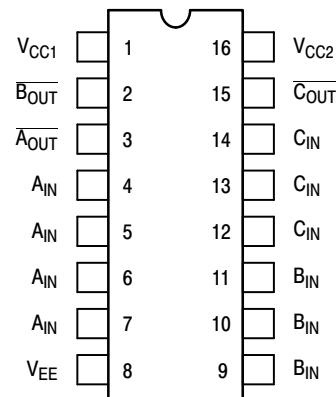


Figure 1. LOGIC DIAGRAM



Pin assignment is for Dual-in-Line Package.

Figure 2. Dip Pin Assignment

Table 1. MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V <sub>EE</sub>	Power Supply (V <sub>CC</sub> = 0)	-8.0 to 0	Vdc
V <sub>I</sub>	Input Voltage (V <sub>CC</sub> = 0)	0 to V <sub>EE</sub>	Vdc
I <sub>out</sub>	Output Current Continuous Surge	50 100	mA
T <sub>A</sub>	Operating Temperature Range	0 to +75	°C
T <sub>stg</sub>	Storage Temperature Range Plastic Ceramic	-55 to +150 -55 to +165	°C °C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 2. ELECTRICAL CHARACTERISTICS (V<sub>EE</sub> = -5.2 V ±5%) (Note 1)

Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
I <sub>E</sub>	Power Supply Current		60		56		60	mA
I <sub>inH</sub>	Input Current High		495		310		310	µA
I <sub>inL</sub>	Input Current Low	0.5		0.5		0.3		µA
V <sub>OH</sub>	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V <sub>OL</sub>	Low Output Voltage	-2.1	-2.03	-2.1	-2.03	-2.1	-2.03	Vdc
V <sub>IH</sub>	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V <sub>IL</sub>	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

1. Each MECL 10H™ series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfm is maintained. Outputs are terminated through a 50 Ω resistor to -2.1 V.

Table 3. AC CHARACTERISTICS

Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
$t_{pd}$	Propagation Delay	0.7	1.5	0.7	1.6	0.7	1.7	ns
$t_r$	Rise Time	0.7	1.6	0.7	1.7	0.7	1.8	ns
$t_f$	Fall Time	0.7	1.6	0.7	1.7	0.7	1.8	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

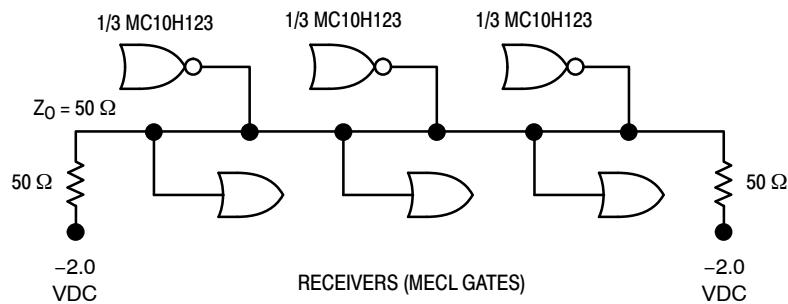


Figure 3. 50 Ω Bus Driver (25 Ω Load)

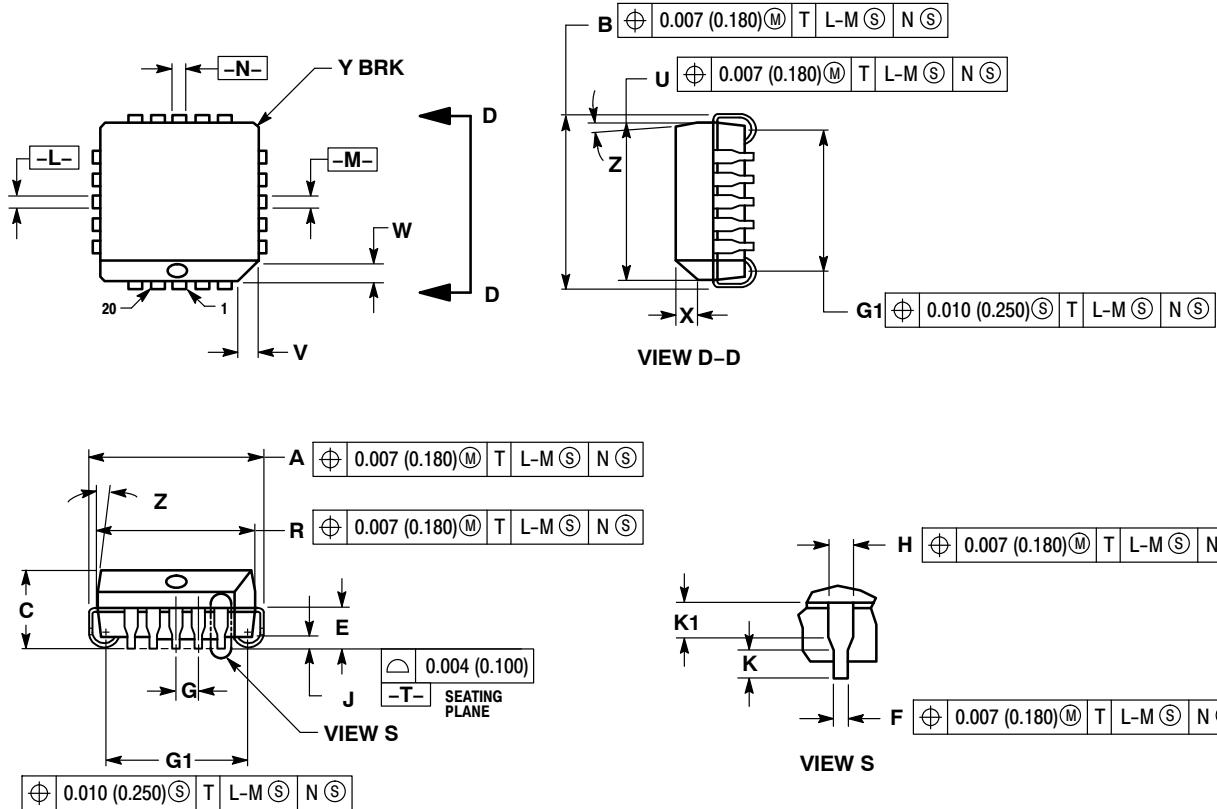
## PACKAGE DIMENSIONS

## 20 LEAD PLLC

FN SUFFIX

CASE 775-02

ISSUE F



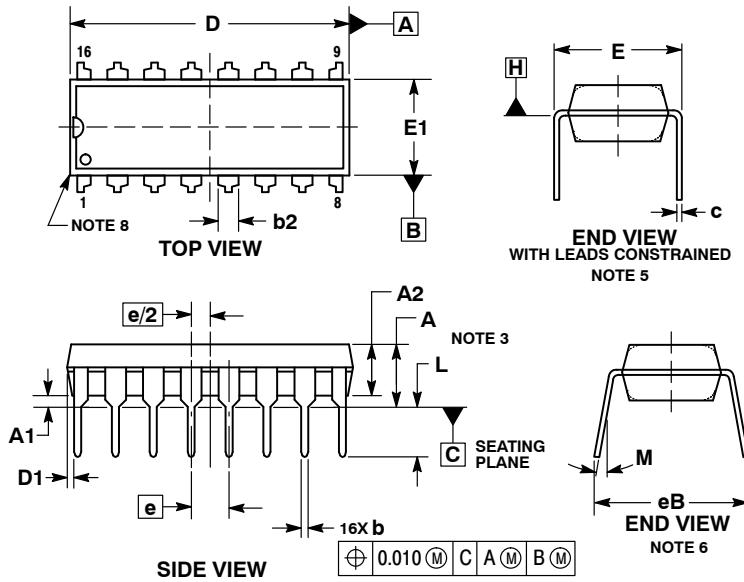
## NOTES:

1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
2. DIMENSIONS IN INCHES.
3. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.021	0.33	0.53
G	0.050	BSC	1.27	BSC
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

## PACKAGE DIMENSIONS

**PDIP-16**  
**P SUFFIX**  
CASE 648-08  
ISSUE V



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEADED IN JEDEC SEATING PLANE GAUGE GS-3.
4. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH.
5. DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR TO DATUM C.
6. DIMENSION eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
7. DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE LEADS, WHERE THE LEADS EXIT THE BODY.
8. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE CORNERS).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	-----	0.210	-----	5.33
A1	0.015	-----	0.38	-----
A2	0.115	0.195	2.92	4.95
b	0.014	0.022	0.35	0.56
b2	0.060	TYP	1.52	TYP
C	0.008	0.014	0.20	0.36
D	0.735	0.775	18.67	19.69
D1	0.005	-----	0.13	-----
E	0.300	0.325	7.62	8.26
E1	0.240	0.280	6.10	7.11
e	0.100	BSC	2.54	BSC
eB	-----	0.430	-----	10.92
L	0.115	0.150	2.92	3.81
M	-----	10°	-----	10°

## STYLE 1:

PIN 1. CATHODE 10. ANODE 10. SOURCE  
2. CATHODE 11. ANODE 11. GATE  
3. CATHODE 12. ANODE 12. SOURCE  
4. CATHODE 13. ANODE 13. GATE  
5. CATHODE 14. ANODE 14. SOURCE  
6. CATHODE 15. ANODE 15. GATE  
7. CATHODE 16. ANODE 16. SOURCE

## STYLE 2:

PIN 1. COMMON DRAIN 2. COMMON DRAIN  
3. COMMON DRAIN 4. COMMON DRAIN  
5. COMMON DRAIN 6. COMMON DRAIN  
7. COMMON DRAIN 8. COMMON DRAIN  
9. GATE 10. SOURCE  
11. GATE 12. SOURCE  
13. GATE 14. SOURCE  
14. SOURCE 15. GATE  
15. GATE 16. SOURCE

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